



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HZK*TWUV70K	A	ZA41	2015-09-18
Amount	UoM	Unit type	ST ECOPACK Grade	
250.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.5X2.16X3.68	1	J bend	
Comment	Package: SMC CLIP (SOD 15 NEW); MDF valid for SMCJ6.0A-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HZK*TWUV70K						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	5.067	mg	supplier	die	Silicon (Si)	7440-21-3		4.909	mg	968818	19636	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	5526	112	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	789	16	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.021	mg	4144	84	
				supplier	metallization	Gold (Au)	7440-57-5		0.020	mg	3947	80	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.028	mg	5526	112	
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.019	mg	3750	76	
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1381	28	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	6118	124	
				Leadframe	Copper and its alloy	88.530	mg	supplier	alloy	Copper (Cu)	7440-50-8		88.487
supplier	alloy	Zinc (Zn)	7440-66-6						0.004	mg	45	16	
supplier	alloy	Iron (Fe)	7439-89-6						0.009	mg	102	36	
supplier	alloy	Phosphorus (P)	12185-10-3						0.030	mg	339	120	
Die Attach	solder	4.215	mg	JIG - R	Lead/Lead Compounds	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.899	mg	925030	15596	
				supplier	soft solder	Tin (Sn)	7440-31-5		0.211	mg	50059	844	
				supplier	soft solder	Silver (Ag)	7440-22-4		0.105	mg	24911	420	
Encapsulation	Other organic material	150.080	mg	supplier	Moulding Compound	Amorphous Silica	7631-86-9		92.149	mg	613999	368596	
				supplier	Moulding Compound	Quartz	14808-60-7		30.016	mg	200000	120064	
				supplier	Moulding Compound	epoxy resin	25068-38-6		18.009	mg	119996	72036	
				supplier	Moulding Compound	phenolic resin	29690-82-2		9.005	mg	60001	36020	
				supplier	Moulding Compound	Carbon black	1333-86-4		0.901	mg	6003	3604	
Finishing	solder	2.108	mg	supplier	connection coating	Tin (Sn)	7440-31-5		2.108	mg	1000000	8432	